



SPECIFICATION

• Supplier : Samsung electro-mechanics • Samsung P/N : CL21F104MBCNNND

• Product : Multi-layer Ceramic Capacitor • Descriptiont : CAP, 100nF, ±20%, 50V, Y5V, 0805

A. Samsung Part Number

<u>CL</u> <u>21</u> <u>F</u> <u>104</u> <u>M</u> <u>B</u> <u>C</u> <u>N</u> <u>N</u> <u>N</u> <u>D</u> ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

1	Series	Samsung Multi-layer Ceramic Capacitor							
2	Size	0805 (inch code	e) L: 2.0	± 0.1	mm	W:	1.25	± 0.1	mm
3	Dielectric	Y5V	8	Inner elec	ctrode		Ni		
4	Capacitance	100 nF		Terminati	ion		Cu		
⑤	Capacitance	±20 %		Plating			Sn 100	0%	(Pb Free)
	tolerance		9	Product			Norma	al	
6	Rated Voltage	50 V	10	Special			Reserv	ved for	future use
7	Thickness	0.85 ± 0.1 mr	m 11	Packagin	g		Cardbo	oard Ty	ype, 13" reel

B. Samsung Reliablility Test and Judgement condition

	Performance	Test condition						
Capacitance	Within specified tolerance	1klb±10% 1.0±0.2Vrms						
Tan δ (DF)	0.05 max.							
Insulation	10,000Mohm or 500Mohm⋅ <i>μ</i> F	Rated Voltage 60~120 sec.						
Resistance	Whichever is Smaller							
Appearance	No abnormal exterior appearance	Microscope (×10)						
Withstanding	No dielectric breakdown or	250% of the rated voltage						
Voltage	mechanical breakdown							
Temperature	Y5V							
Characterisitcs	(From -30 ℃ to 85 ℃, Capacitance change shoud be within -82~+22%)							
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.						
of Termination	terminal electrode							
Bending Strength	Capacitance change : within ±30%	Bending to the limit (1mm)						
		with 1.0mm/sec.						
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder						
	is to be soldered newly	245±5℃, 3±0.3sec.						
		(preheating : 80~120℃ for 10~30sec.)						
Resistance to	Capacitance change : within ±20%	Solder pot : 270±5°C, 10±1sec.						
Soldering heat	Tan δ, IR : initial spec.							

	Performance	Test condition				
Vibration Test	Capacitance change: within ±20%	Amplitude: 1.5mm				
	Tan δ, IR : initial spec.	From 10Hz to 55Hz (return : 1min.)				
		2hours × 3 direction (x, y, z)				
Moisture	Capacitance change: within ±30%	With rated voltage				
Resistance	Tan δ : 0.09 max	40±2℃, 90~95%RH, 500+12/-0hrs				
	IR: 500Mohm or 25Mohm · μF					
	Whichever is Smaller					
High Temperature	Capacitance change: within ±30%	With 200% of the rated voltage				
Resistance	Tan δ : 0.09 max	Max. operating temperature				
	IR : 1000Mohm or 50Mohm $\cdot \mu$ F					
	Whichever is Smaller	1000+48/-0hrs				
Temperature	Capacitance change : within ±20%	1 cycle condition				
Cycling	Tan δ, IR : initial spec.	Min. operating temperatur → 25°C				
		→ Max. operating temperature → 25°C				
		5 cycle test				

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5 $^{\circ}\!\!\mathrm{C}$, 10sec. Max)

^{*} For the more detail Specification, Please refer to the Samsung MLCC catalogue.